



On-shore Advanced Packaging Capabilities GOMACTech-2024

18 March 2024

TIME (EDT)	TOPICS
1300 to 1315	Onshoring Workshop Overview
1315 to 1340	RESHAPE Overview
Funded Onshoring Capabilities by RESHAPE/ Title III (20 minutes each; questions addressed in the panel/forum)	
1340 to 1350	Introduction of presenters with the highlighted RESHAPE element addressed
1350 to 1410	Bridg/ Skywater (Si Interposer standup; IMEC license transfer to the Bridg/Skywater facility)
1410 to 1430	Neocity (fan out wafer level packaging standup; DECA license transfer to the Bridg/Skywater facility)
1430 to 1450	Micross (300mm wafer prep/bumping standup)
1450 to 1505	Break
1505 to 1525	Calumet (HDBU/HDI standup)
1525 to 1545	GreenSource (HDBU/HDI standup)
1545 to 1630	Open forum/ Panel of 5 performers including the tri-service RESHAPE team, NGMS, BAE